INTERFERRENCE

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L37	1	(trace and package and hole and fill$4 and mesh and structure and adjacent and align$3 and packag$4 and layout).CLM.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 19:59

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	77892	electronic same packag$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 19:49
L2	1184	(electronic same packag$4) same power same ground	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 19:49
L3	80	(electronic same packag$4 same power same ground) and mesh	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 19:49
L4	31	(electronic same packag$4 same power same ground) and mesh and hole	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 19:49
L5	94	(electronic same packag$4 same mesh) and hole	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 19:49
L6	57	(electronic same packag$4 same mesh) and hole and power	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 19:49
L7	9	(electronic same packag$4 same mesh) and hole and power and trace	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 19:49
L8	3143	(electronic same packag$4) and hole and power and trace	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 19:49

| L9	312	(electronic same packag$4) and mesh and hole and power and trace	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 19:49
L10	182	(electronic same packag$4) and mesh and hole and power and trace and ground	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 19:49
L11	149	(electronic same packag$4) and mesh and hole and power and trace and ground and align$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 19:49
L12	492	(electronic same packag$4) and (trace same plane) and (trace same hole)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 19:49
L13	43	(electronic same packag$4) and (trace same plane) and (trace same hole) and mesh	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 19:49
L14	16	(electronic same packag$4) and (trace same plane) and (trace same hole) and mesh and ("716"/$.ccls. or "257"/$.ccls.)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 19:49
L15	211	trace near4 (fill or filling or filled) same metal	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 19:49
L16	119	trace near4 (fill or filling or filled) same metal and signal	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 19:49

L17	1792	(trace near4 vias) and package and hole	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 19:49
L18	1139	(trace near4 vias) and package and hole and fill$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 19:49
L19	97	(trace near4 vias) and package and hole and fill$4 and mesh	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 19:52
L20	41	(trace near4 vias) and package and hole and fill$4 and (prevent near4 (noise or interfer$6))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 19:49
L21	50	(trace near4 vias) and package and hole and (prevent near4 (noise or interfer$6))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 19:49
L22	114	(trace near4 vias) and hole and (prevent near4 (noise or interfer$6))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 19:49
L23	5	(trace near4 vias) same (prevent near4 (noise or interfer$6))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 19:49
L24	0	(trace near4 vias) same (prevent near4 (noise or interfer$6)) and singal and compar$4 and power	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 19:49

L25	0	(trace near4 vias) same (prevent near4 (noise or interfer$6)) and singal and compar$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 19:49
L26	1	(trace near4 vias) same (prevent near4 (noise or interfer$6)) and signal and compar$4 and power	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 19:49
L27	2	(trace near4 vias) same (prevent near4 (noise or interfer$6)) and signal and compar$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 19:49
L28	0	(trace near4 vias) same (prevent near4 (noise or interfer$6)) and signal and compar$4 and hole	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 19:49
L29	71	(trace near4 vias) and package and hole and fill$4 and mesh and adjacent and align$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 19:55
L30	1480	716/8,11.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 19:53
L31	31	716/8,11.ccls. and trace and fill	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 19:54
L32	5	716/8,11.ccls. and trace and fill and hole and plane	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 19:54

L33	17	(trace near4 vias) and package and hole and fill$4 and mesh and adjacent and align$3 and packag$4 and layout	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 19:57
L34	0	((trace near4 vias) and package and hole and fill$4 and mesh and adjacent and align$3 and packag$4 and layout).CLM.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 19:56
L35	260	trace and package and hole and fill$4 and mesh and adjacent and align$3 and packag$4 and layout	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 20:00
L37	1	(trace and package and hole and fill$4 and mesh and structure and adjacent and align$3 and packag$4 and layout).CLM.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 19:59
L38	15	trace and package and hole and fill$4 and (mesh same plane) and adjacent and align$3 and packag$4 and layout	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 20:01

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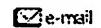
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